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(54) Title: LAMINATED SOCKET CONTACTS

(57) Abstract: A laminated socket contact is described for reducing inductance in power connections to an integrated circuit package. The contact consists of a conductive power panel, a conductive ground panel, a thin non-conductive layer interposed between the power panel and ground panel layer, and at least one conductive finger extending from each of the power panel and ground panel. Various embodiments of this socket contact may be used with power bar connectors, side terminal connectors or pin connectors.

LAMINATED SOCKET CONTACTS

FIELD OF THE INVENTION

[0001] The invention relates generally to the field of integrated circuit socket
5 design. More particularly, the invention relates to a laminated socket contact that reduces
the inductance of the package/sockets by reducing the distance between power and ground
conductors of the contact.

BACKGROUND OF THE INVENTION

10

[0002] Various methods of mounting integrated circuit packages onto printed
circuit boards have been developed. For example, common methods employ some form of
socket, mounted onto a printed circuit board, into which the integrated circuit package is
placed. Pins on the integrated circuit package mate with corresponding receptacles in the
15 socket. Through these pins, power, ground, input, and output signals are supplied to the
integrated circuit.

[0003] Improvements to the various types of sockets used to mount integrated
circuit packages have focused on reducing the amount of electrical resistance presented by
the contacts within the sockets. Various improvements have focused on increasing the
20 contact area and/or the contact pressure in order to provide low resistance connections.

[0004] However, the power and ground connection points of these various types of
sockets are relatively far apart and the conductors carrying the current are relatively long.
This distance between connection points and length of conductor increase the amount of
inductance in the conductors.

BRIEF DESCRIPTION OF THE DRAWINGS

- [0005] The appended claims set forth the features of the invention with
5 particularity. The invention, together with its advantages, may be best
understood from the following detailed description taken in conjunction
with the accompanying drawings of which:
- [0006] **Figure 1** is a high level illustration of a typical socket and integrated circuit
package;
- 10 [0007] **Figure 2** is a high level illustration of a socket and integrated circuit
package having a power bar;
- [0008] **Figures 3a and 3b** illustrate an integrated circuit package having a power
bar;
- [0009] **Figure 4** illustrates a socket for mounting an integrated circuit with a power
15 bar;
- [0010] **Figure 5** illustrates how an integrated circuit package with a power bar may
be mounted in a socket;
- [0011] **Figure 6a** is a top view of an integrated circuit package with side terminal
connections;
- 20 [0012] **Figure 6b** is a side view of an integrated circuit package with side terminal
connections;
- [0013] **Figure 6c** is an alternative top view of an integrated circuit package with
side terminals connections;
- [0014] **Figure 7** is a side view illustrating how an integrated circuit package with
25 side terminals may be mounted in a socket;

[0015] **Figure 8** is a side view illustrating a laminated socket contacting with a power bar according to one embodiment of the present invention;

[0016] **Figure 9** is a top view illustrating a laminated socket contacting with a power bar according to one embodiment of the present invention;

5 [0017] **Figure 10** is a side view illustrating a laminated socket contact with terminals for connecting to an integrated circuit package with side terminal connections according to one embodiment of the present invention; and

[0018] **Figure 11** is a top view illustrating a laminated socket contact connecting with an integrated circuit package having side terminal connections
10 according to one embodiment of the present inventions.

DETAILED DESCRIPTION OF THE INVENTION

[0019] A laminated socket contact is described for reducing inductance in power
15 connections to an integrated circuit package. Broadly stated, embodiments of the present invention seek to provide a more efficient power socket by reducing the distance between the power and ground contacts. According to one embodiment, the contact consists of a conductive power panel, a conductive ground panel, a thin non-conductive layer interposed between the power panel and ground panel layer, and at least one conductive finger
20 extending from each of the power panel and ground panel. Various embodiments of this socket contact may be used with power bar connectors, side terminal connectors or pin connectors.

[0020] In the following description, for the purposes of explanation, numerous specific details are set forth in order to provide a thorough understanding of the present
25 invention. It will be apparent, however, to one skilled in the art that the present invention

may be practiced without some of these specific details. In other instances, well-known structures and devices are shown in block diagram form.

[0021] Importantly, while embodiments of the present invention will be described with reference to power bar connectors and side terminal connectors for integrated circuit (IC) packages, the method and apparatus described herein are equally applicable to other types of connectors used for electrically connecting an integrated circuit package to a socket. For example, the techniques described herein are thought to be useful in connection with traditional integrated sockets using pin receptacles such as the 478 sockets manufactured by Intel Corporation of Santa Clara California for use with that company's P4 processors.

[0022] **Figure 1** is a high level illustration of a typical socket and integrated circuit package. This example illustrates an integrated circuit package 111 having a number of pins 101 for providing electrical connection between the integrated circuit package 111 and a socket 110. When connecting the integrated circuit package 111 to the socket 110, all of the package pins 101 are inserted into and engage a socket's pin receptacles 102. A lever 103 is used for locking the package pins 101 into place and forcing contact between the pins 101 and their corresponding receptacles 102.

[0023] The pin size has been reduced over time due to chip complexity, solder re-flow and packaging advances such as surface mount technology (SMT). Increased functionality has resulted in increased power demands by the IC device to the point where power and ground must be supplied through multiple pins. However, the pin size and the contacts between the socket pin receptacle and the package pin limit the power that may be supplied to an IC from an IC board. Additionally, the individual pins cause high non-uniform current distribution between the different pins that are utilized to supply the power

to the IC package. One solution to these problems is the use of a power bar for supplying power and ground connections to the IC package.

[0024] **Figure 2** is a high level illustration of a socket and integrated circuit package having a power bar. In this example, an IC package 201 having a power plane (not shown) is mounted into a socket 203. The IC package 201 has multiple input/output pins 204 that are inserted into corresponding socket holes 205 for transferring and receiving informational input/output (I/O) signals necessary for the proper functional operation of the IC chip 206 integrated with the IC package 201. Although other electrically conductive materials may be used, in this example a Copper (Cu) power bar 207 is connected to the power plane 202 along its entire adjacent border 208 and extrudes from the IC package to be inserted into a corresponding power bar carrier 209 incorporated in the socket 203. This power bar provides common connection points for all power and ground inputs to the IC chip 206. A locking mechanism 210 is employed to force the I/O pin receptacle contacts to make contact with their corresponding pins, while a second locking mechanism 211 may be employed to separately lock the power bar carrier to the power bar.

[0025] **Figures 3a and 3b** illustrate an integrated circuit package having a power bar. Although various planes or cross planes may exist in the package for holding the power and ground for the IC, Figure 3a demonstrates two power planes, one for holding a first voltage level and one for holding a second voltage level. For simplicity these voltage levels will be referred to as power and ground. Arbitrarily, the power plane 301 resides above the ground plane 302 although it is well understood that location is irrelevant. Additionally, a plane in this context is one level of copper although a plane that is not restricted to copper or a single level is contemplated. For example, a ground plane could be constructed of any conducting material and spread among several levels in the IC

package 303. The ground power plane's extrusion panel 304 could connect directly to one or more of the ground planes along its entire adjacent edge 311 to the ground plane.

[0026] In this example, a power bar 310 comprises two power plane extrusion panels 304 and 305 that are separated by an insulating buffer panel 306 for protecting the integrity of the power signals to be delivered by preventing short circuiting. The ground power plane extrusion panel 304 is connected along its entire adjacent bordering edge 311 to the ground power plane 302 by solder or equivalent while the power plane extrusion panel 305 is connected along its entire adjacent bordering edge to the power plane 301 via solder or equivalent. An insulation barrier panel 307 along the perpendicular circumference of the power plane extrusion panel 305 isolates the power plane extrusion panel 305 from the ground plane 302 where the power plane extrusion panel 305 penetrates or passes through the ground plane 302.

[0027] Each power or ground extrusion panel 304 or 305 of the power bar 310 may have various contact extrusions, bumps or ridges to enable intentional engaging of the IC package power bar to a socket. In this example, several protrusions in the form of regularly spaced bumps or ridges 309 are integrally connected and formed as part of the power or ground extrusion panels to assist in the intentional engaging or locking in place of the IC package power bar to the socket carrier.

[0028] The power bar removes the inherent limitations of transferring power to an IC through pins by providing a larger surface and contact area. The increased surface and contact area provides substantial power delivery capabilities while also providing a uniform delivery mechanism that reduces resistance and inductance caused by multiple pins.

[0029] **Figure 4** illustrates a socket for mounting an integrated circuit with a power bar. In this example, the carrier 410 has two electrically conducting side panels 401 and

402 separated by a non-conductive insulation bar 403. The non-conductive insulating material may be formed from one mold or pieced together to hold the various conductive power bar carriers and pin receptacles (not shown). The electrically conducting side panels 401 and 402 are separated by insulation in order to accommodate both power and ground power plane extrusion panels 304 and 305 from a package power bar. The socket may ultimately be placed on an IC board, such as a Central Processing Unit (CPU) motherboard. As the design contemplates use in a solder-flow process used by existing technologies, such as SMT, the mounting pads 405 on the bottom of the socket are produced by known methods and are spaced as required.

10 [0030] **Figure 5** illustrates how an integrated circuit package with a power bar may be mounted in a socket. The power bar 501 in this example is made of several segments 502, each designed to correspond with contact portions 503 of a carrier 504. The power bar 501 is initially set into the carrier such that it begins in a position where no contact is made. Upon sliding the power bar into position, each of the segments align with their corresponding contacts and the spring portion of the carrier's contacts apply the force necessary to establish the electrical connection.

[0031] Therefore the power bar can provide connection points for power and ground connections that are mechanically more substantial than the pins of the typical IC package as described above with reference to figure 1. Since these connection points are larger and stronger, they may have much more force applied to them, thereby reducing the electrical resistance of the contact. By reducing the electrical resistance of the contacts, a more uniform distribution of power can be achieved. However, the power and ground connection points are relatively far apart and the conductors carrying the current supplied by the power bar are relatively long. This distance between connection points and length of conductor increase the amount of inductance in the conductors. The present invention, as

will be described below, reduces the amount of inductance in such connections by reducing the distance between the connection points and the length of the conductors.

[0032] The power bar design is not the only design to be affected by increased inductance due to a relatively large distance between the power and ground contacts and relatively long conductors for the power and ground. IC packages utilizing side terminals for supplying power and ground are likewise affected. Therefore, embodiments of the present invention are equally applicable to IC packages utilizing side terminals as well as other designs.

[0033] **Figure 6a** is a top view of an integrated circuit package with side terminal connections. In this example, an IC package 600 is illustrated that includes an integrated circuit die or chip 605. As with the other types of IC packages discussed above, pins (not shown) may be present to provide electrical connection points for input and output signals to and from the IC die 605. The side terminals 610 and 615, similar to the two halves of the power bar, provide connection points for power and ground being supplied to the IC die 605.

[0034] **Figure 6b** is a side view of an integrated circuit package with side terminal connections. This example illustrates the same IC package 600 including an IC die or chip 605 and side terminal connections 610 and 615. Visible from this perspective are a number of shunts 620 connected to the side terminals. These shunts 620 are used to distribute power and ground to appropriate connection points on the IC die 605.

[0035] **Figure 6c** is an alternative top view of an integrated circuit package with side terminals connections. In this example, an IC package 600 is illustrated that includes an IC die 605 and a number of side terminals 605 and 615. The difference here is that the side terminals 605 and 615, instead of extending the entire length of the IC package 600, are divided into a number of smaller segments. These segments 605 and 615 may be

arranged so that all power terminals are on one side of the IC package 600 and all ground terminals are on the other side. Alternatively, the segments 605 and 615 may be arranged so that segments on each side provide connection points for power and ground alternately. This arrangement will be beneficial but not necessary for implementing embodiments of
5 the present invention.

[0036] **Figure 7** is a side view illustrating how an integrated circuit package with side terminals may be mounted in a socket. This example illustrates a socket 720 mounted on a motherboard 725. An IC package 700 containing an IC chip 705, side terminals 710 and a number of pins 715 is also shown. When the IC package 700 is inserted into the
10 socket 720, the pins 715 on the IC package 700 mate with appropriate receptacles in the socket 720 providing input and output connections for the IC chip 705. The side terminals 710 on the IC package 700 mate with terminals 730 mounted on and extending from the socket 720 to provide power and ground to the IC chip 705.

[0037] Therefore, as with the power bar, the side terminals can provide connection
15 points for power and ground connections that are mechanically more substantial than the pins of the typical IC package as described above with reference to figure 1. Since these connection points are larger and stronger, they may have much more force applied to them, thereby reducing the electrical resistance of the contact. By reducing the electrical resistance of the contacts, a more uniform distribution of power can be achieved. However,
20 the power and ground connection points are relatively far apart and the conductors carrying the current supplied by the power bar are relatively long. This distance between connection points and length of conductor increase the amount of inductance in the conductors. The present invention, as will be described below, reduces the amount of inductance in such connections by reducing the distance between the connection points and the length of the
25 conductors.

[0038] **Figure 8** is a side view illustrating a laminated socket contacting with a power bar according to one embodiment of the present invention. In this example, a laminated socket contact 800 is illustrated. Additional details of this contact will be apparent in figure 9. Figure 8 depicts a number of power 805 and ground 810 connections
5 extending from the body of the contact 800. In this example, the power contacts 805 and the ground contacts 810 alternate. These power 805 and ground 810 contacts mate with corresponding terminals 815 and 820 on a power bar 825 extending from an IC package (not shown) when the IC package 825 is inserted into a socket (not shown) utilizing the laminated socket contact 800.

10 [0039] **Figure 9** is a top view illustrating a laminated socket contacting with a power bar according to one embodiment of the present invention. In this view, additional details of the laminated socket contact 900 and 905 become apparent. Here, segments of a power bar 910 are illustrated. Each power bar segment 910 is made up of a ground 915 and a power 925 conductive side panel with a non-conductive insulation bar 910 between the
15 side panels 915 and 925 as explained above. The conductive side panels 915 and 925 are arranged so that each successive power bar segment 910 has the power conductive side panel 925 and the ground conductive side panel 915 on alternate sides.

[0040] Two laminated socket contacts 900 and 905 are shown. Each laminated socket contact 900 and 905 is made up of a power panel 940 and a ground panel 930. The
20 power panel 940 and ground panel are brought into close proximity to one another within the body of the laminated socket contact 900 and 905 but are separated from each other by a thin non-conductive layer 935. According to one embodiment of the present invention, this material may be polymer based non-conductive adhesive 2-4 mils thick. The power panel, ground panel and non-conductive layer are held together by the adhesive, which acts

as the bonding material for the two metal planes and the insulation layer for the power and ground.

[0041] Extending above each power panel 940 and ground panel 930 are a number of conductive fingers 945 and 950 for engaging and electrically contacting the conductive side panels 915 and 925 of the power bar segments 910. In this configuration, the power
5 panel 940 and ground panel 930 of the laminated socket contact 900 and 905 resemble the conducting side panels 401 and 402 of the power bar socket 410 illustrated in figure 4. However, the fingers 950 and 945 extending from the power panel 940 and the ground panel 930 of the laminated socket contact 900 and 905 all extend in the same direction and
10 alternate fingers connect with power panels and ground panels, respectively. This arrangement allows for the elimination of the non-conductive insulation bar 403 illustrated in figure 4. The power panel 940 and ground panel 930 can then be brought into close proximity, separated only by the thin non-conductive layer 935. This reduces the distance between power and ground conductors, reduces the over length of the conductors and
15 thereby reduces the amount of inductance through the conductors.

[0042] **Figure 10** is a side view illustrating a laminated socket contact with terminals for connecting to an integrated circuit package with side terminal connections according to one embodiment of the present invention. In this example, a laminated socket contact 1000 is shown mounted on a motherboard 1020 via solder balls 1005.
20 Alternatively, the laminated socket contact may be mounted within a socket which is in turn mounted on a motherboard.

[0043] The laminated socket contact consists of a power panel 1010 and a ground panel 1015 brought into close proximity but separated by a thin, non-conductive layer 1035. As with the laminated socket contact configured to couple with a power bar, this
25 non-conductive layer may be made be a polymer based non-conductive adhesive 2-4 mils

thick. The power panel, ground panel and non-conductive layer are held together by the adhesive, which acts as the bonding material for the two metal planes and the insulation layer for the power and ground. Extending above the laminated socket contact are a power finger 1030 and a ground finger 1040 each respectively connected to the power panel and the ground panel. These fingers provide the electrical connection to the side terminals of an integrated circuit package.

[0044] **Figure 11** is a top view illustrating a laminated socket contact connecting with an integrated circuit package having side terminal connections according to one embodiment of the present inventions. In this example, an integrated circuit package 1100 with side terminations 1120 and 1125 is illustrated. The side terminations are arranged so that alternate terminations provide connection to power and ground, respectively. The laminated socket contacts, either mounted on a motherboard or within a socket body, are arranged so that the power fingers and grounds fingers of each laminated socket contact will connect with corresponding power and ground side terminals on the IC package when the IC package is inserted into the socket or mounted on the motherboard. This arrangement reduces the distance between power and ground conductors, reduces the over length of the conductors and thereby reduces the amount of inductance through the conductors.

20

CLAIMS

What is claimed is:

1. A socket contact comprising:
5 a conductive power panel;
a conductive ground panel;
a thin non-conductive layer interposed between the power panel and ground panel layer; and
at least one conductive finger extending from each of the power panel and ground
10 panel.
2. The socket contact of claim 1, further comprising a plurality of conductive fingers alternately extending from each of the power panel and ground panel in the same direction.
3. The socket contact of claim 2, wherein the plurality of fingers are positioned to
15 engage segments of a power bar.
4. The socket contact of claim 3, wherein the non-conductive material comprises a polymer based non-conductive adhesive.
5. The socket contact of claim 4, wherein the non-conductive layer is 2-4 mils thick.
6. The socket contact of claim 3, wherein the power panel and ground panel are
20 bound together by the polymer based non-conductive adhesive.

7. The socket contact of claim 1, wherein the at least one conductive finger extending from each of the power panel and ground panel are positioned to engage side terminals on an integrated circuit package.
8. The socket contact of claim 7, wherein the non-conductive material comprises a polymer based non-conductive adhesive.
9. The socket contact of claim 8, wherein the non-conductive material is 2-4 mils thick.
10. The socket contact of claim 7, wherein the power panel and ground panel are bound together by the polymer based non-conductive adhesive.
11. A socket comprising:
a conductive power panel;
a conductive ground panel;
a thin non-conductive layer interposed between the power panel and ground panel layer;
a socket body encompassing and binding together the power panel, ground panel, and non-conductive layer; and
a plurality of conductive fingers alternately extending from each of the power panel and ground panel in the same direction to engage segments of a power bar.
12. The socket of claim 11, wherein the non-conductive layer comprises a polymer based non-conductive adhesive.

13. The socket of claim 12, wherein the non-conductive layer is 2-4 mils thick.
14. An integrated circuit package comprising:
an integrated circuit; and
a power bar to supply power and ground signals to the integrated circuit, the power
5 bar comprising a conductive power side panel and a conductive ground side
panel separated by a non conductive insulation bar wherein segments of the
conductive power side panel and segments of the conductive ground panel
are on alternate sides of the power bar.
15. The integrated circuit package of claim 14, wherein the power bar is arranged to
10 engage a socket comprising:
a conductive power panel;
a conductive ground panel;
a thin non-conductive layer interposed between the power panel and ground panel
layer;
15 a socket body encompassing and binding together the power panel, ground panel,
and non-conductive layer; and
a plurality of conductive fingers alternately extending from each of the power panel
and ground panel in the same direction wherein the plurality of fingers are
positioned to engage segments of the power bar.
- 20 16. The integrated circuit package of claim 15, wherein the non-conductive layer
comprises a polymer based non-conductive adhesive.

17. The integrated circuit package of claim 16, wherein the non-conductive layer is 2-4 mils thick.
18. A socket comprising:
at least one conductive power panel;
5 at least one conductive ground panel;
at least one thin non-conductive layer interposed between each of the at least one power panel and at least one ground panel layer;
a socket body encompassing and binding together the at least one power panel, at least one ground panel, and at least one non-conductive layer; and
10 a conductive finger extending from each of the power panel and ground panel in the same direction to engage side terminals on an integrated circuit package.
19. The socket of claim 18, wherein the non-conductive layer comprises a polymer based non-conductive adhesive.
- 15 20. The socket of claim 19, wherein the non-conductive layer is 2-4 mils thick.
21. An integrated circuit package comprising:
an integrated circuit; and
a plurality of side terminations to supply power and ground signals to the integrated circuit, the side terminations arranged to alternately contact a power
20 conductor and a ground conductor.

22. The integrated circuit package of claim 21, wherein the side terminations are arranged to engage a socket comprising:
- at least one conductive power panel;
 - at least one conductive ground panel;
 - 5 at least one thin non-conductive layer interposed between each of the at least one power panel and at least one ground panel layer;
 - a socket body encompassing and binding together the at least one power panel, at least one ground panel, and at least one non-conductive layer; and
 - 10 a conductive finger extending from each of the power panel and ground panel in the same direction to engage the side terminations.
23. The integrated circuit package of claim 22, wherein the non-conductive layer comprises a polymer based non-conductive adhesive.
24. The integrated circuit package of claim 23, wherein the non-conductive layer is 2-4 mils thick.

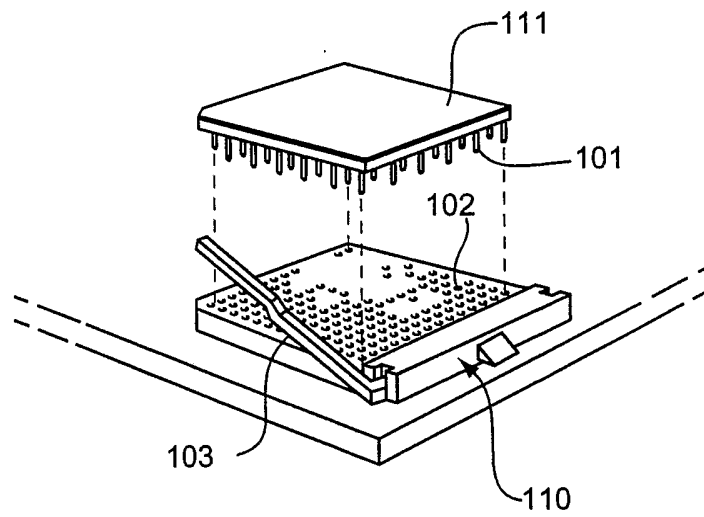


FIG. 1

2/11

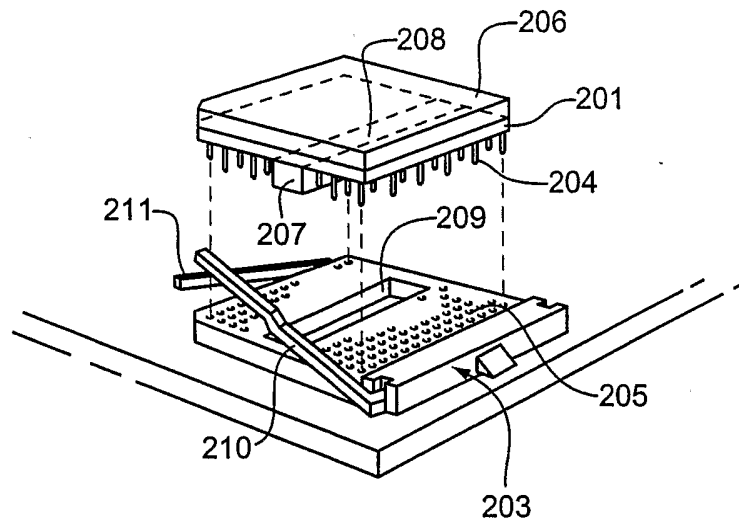


FIG. 2

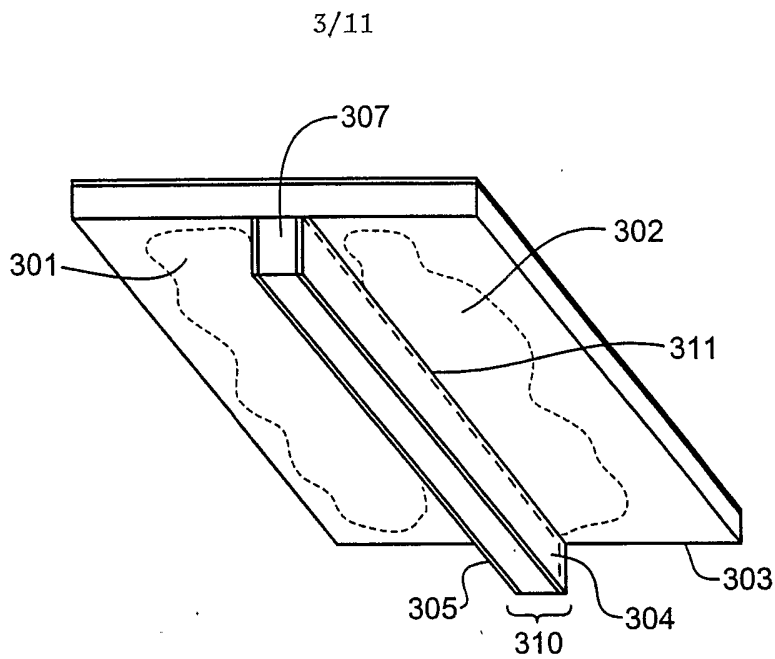


FIG. 3A

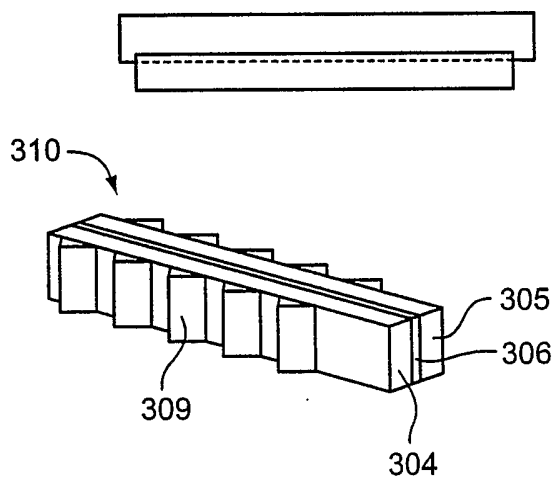


FIG. 3B

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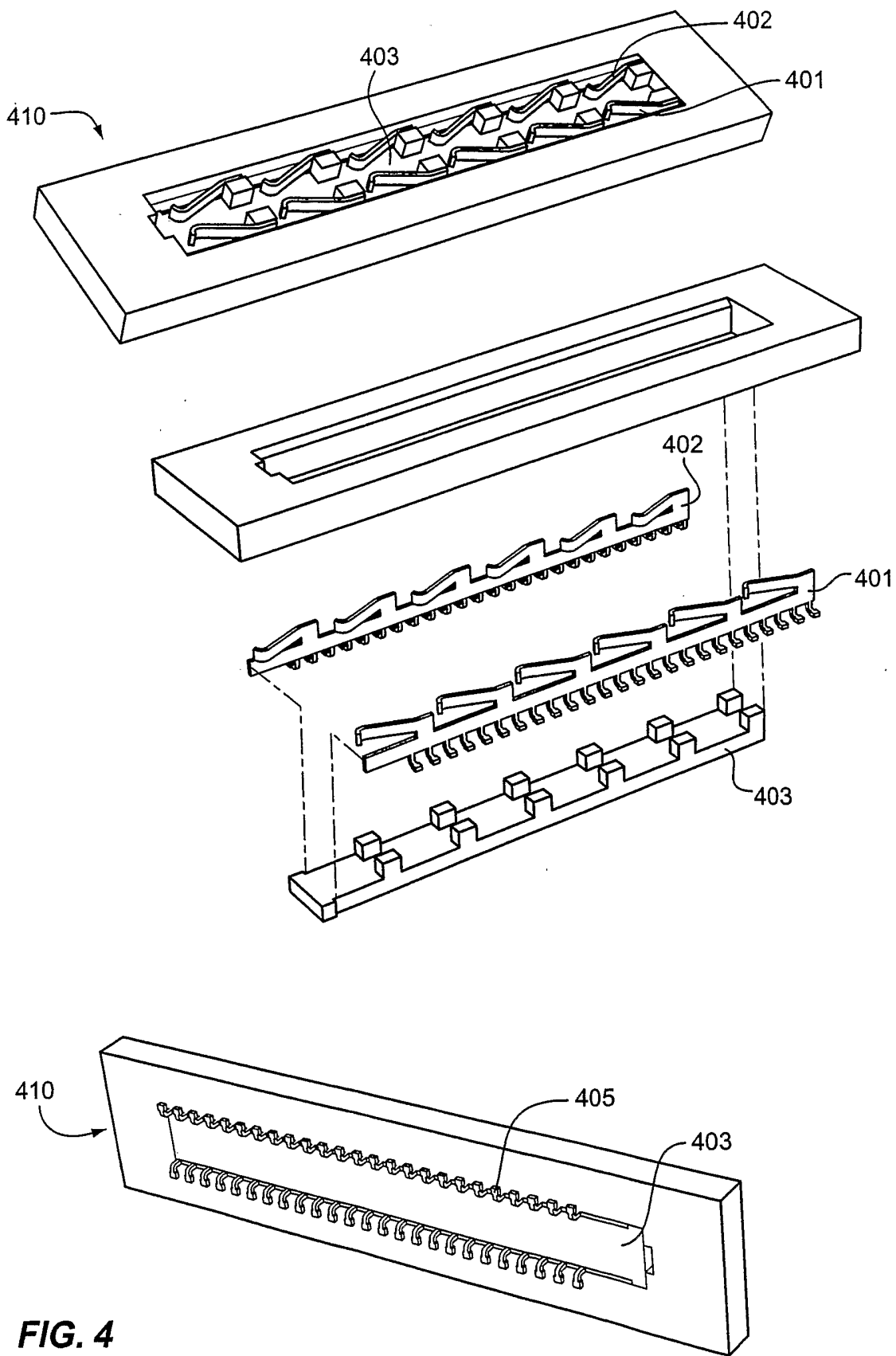


FIG. 4

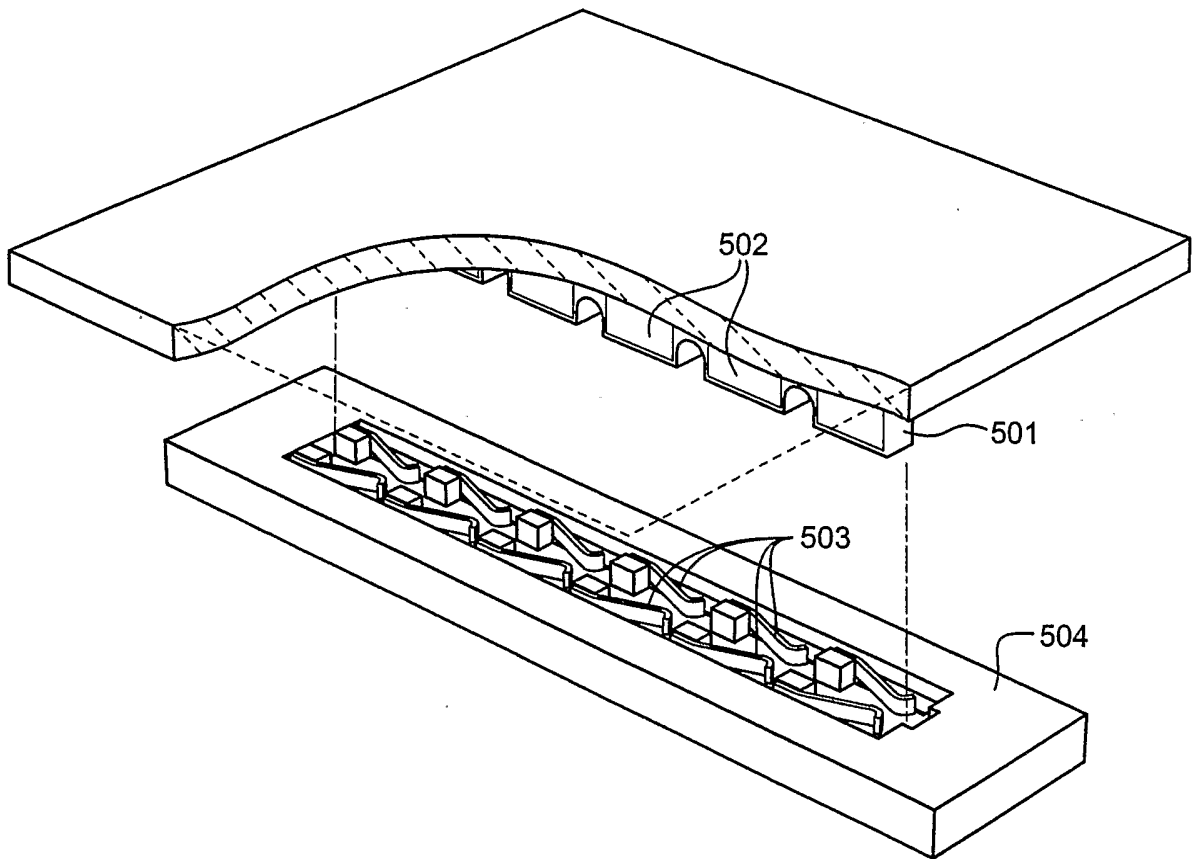


FIG. 5

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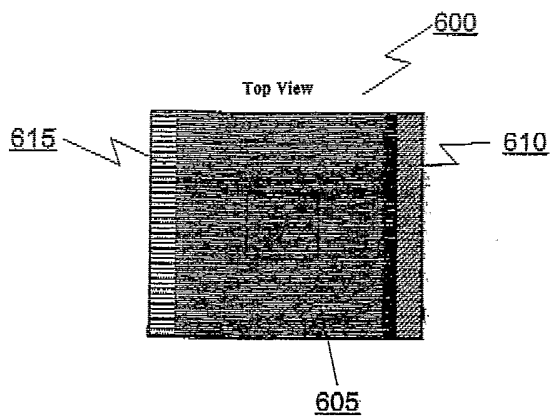


Figure 6a

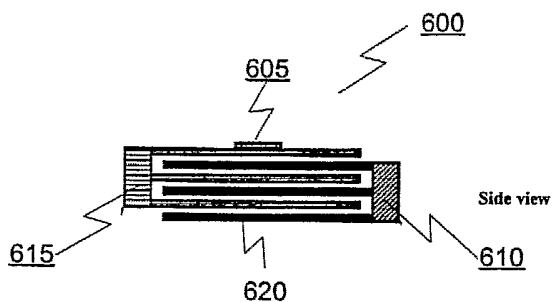


Figure 6b

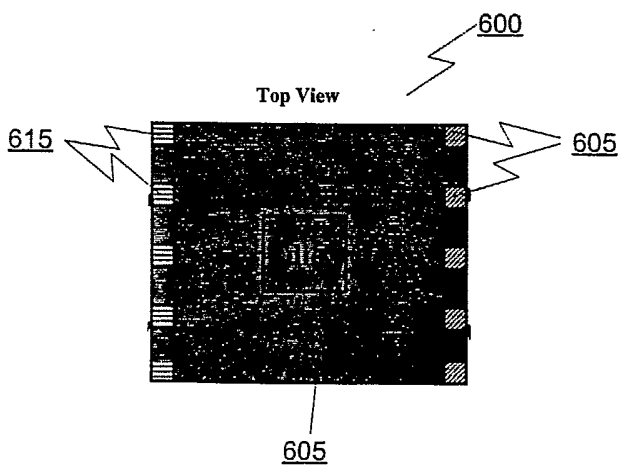


Figure 6c

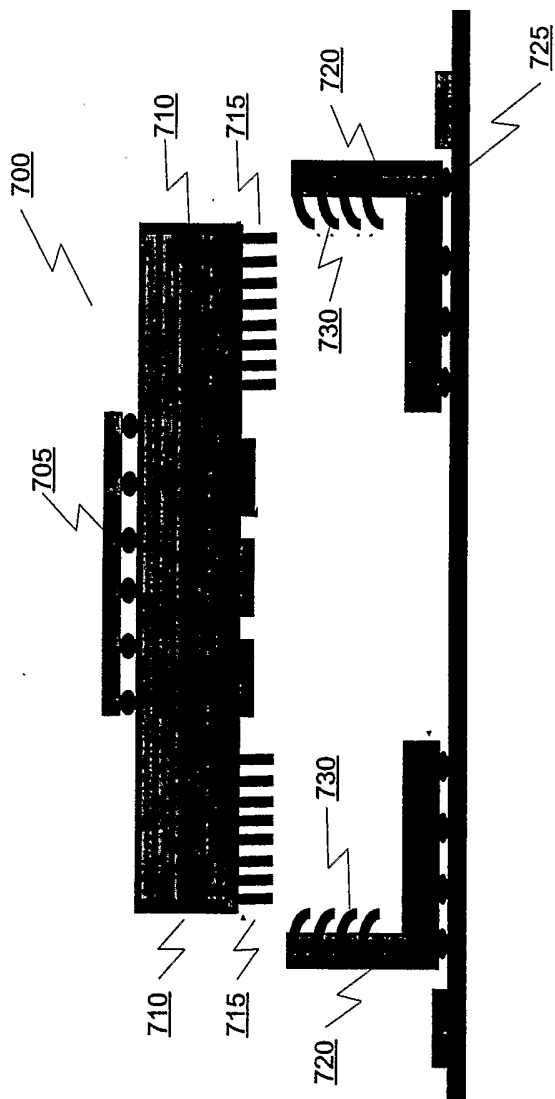
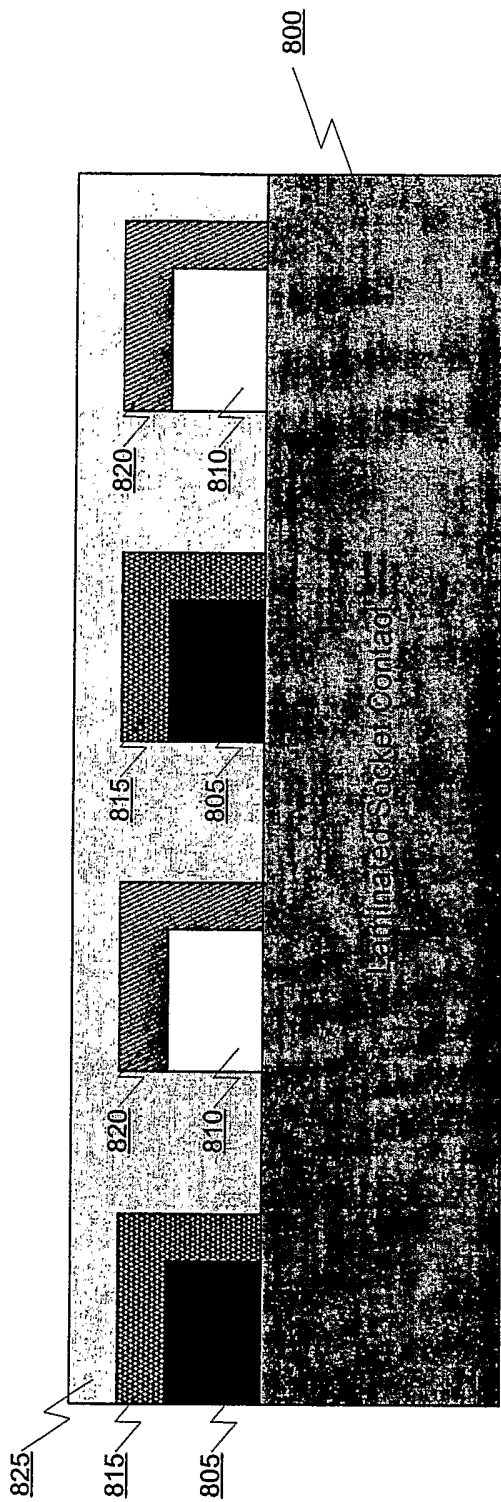


Figure 7



Side View

Figure 8

9/11

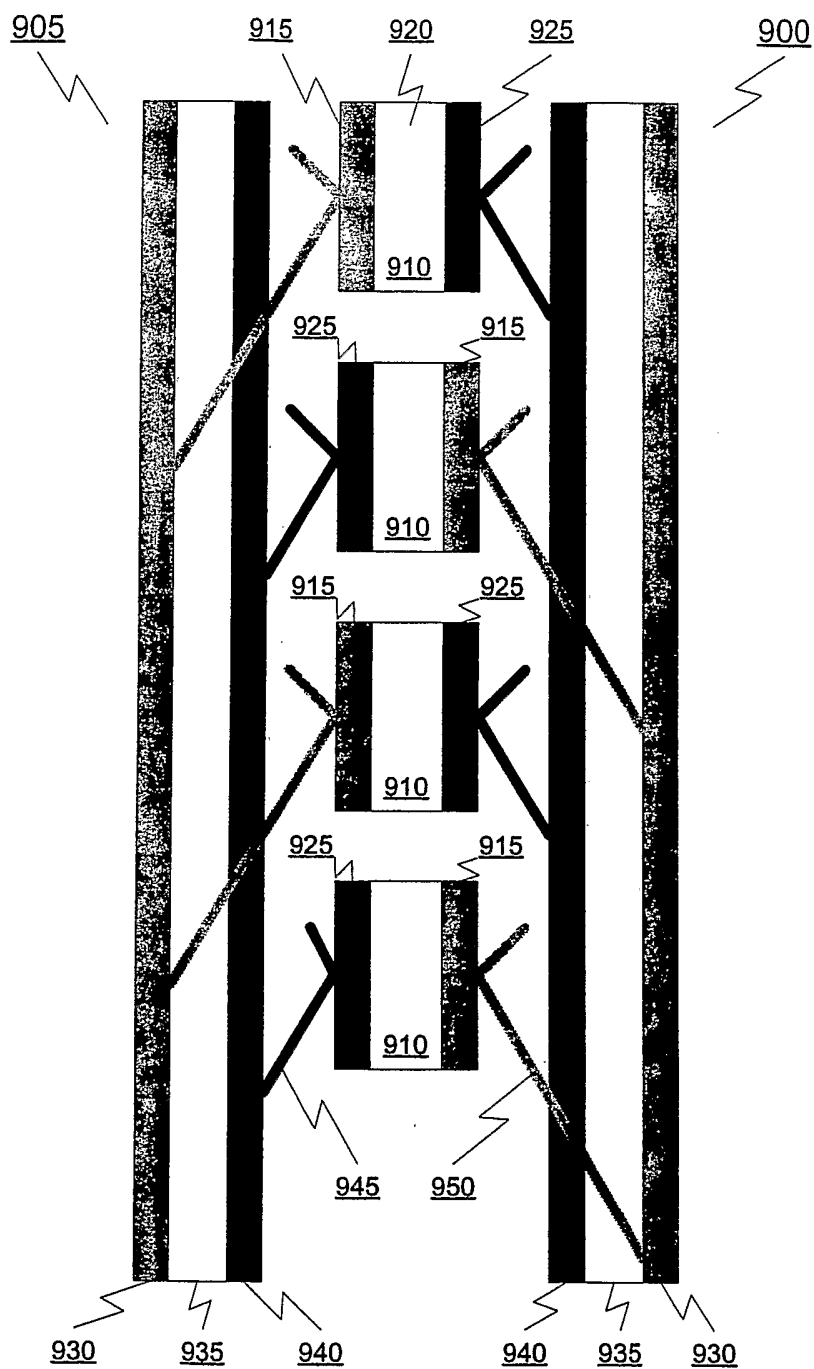


Figure 9

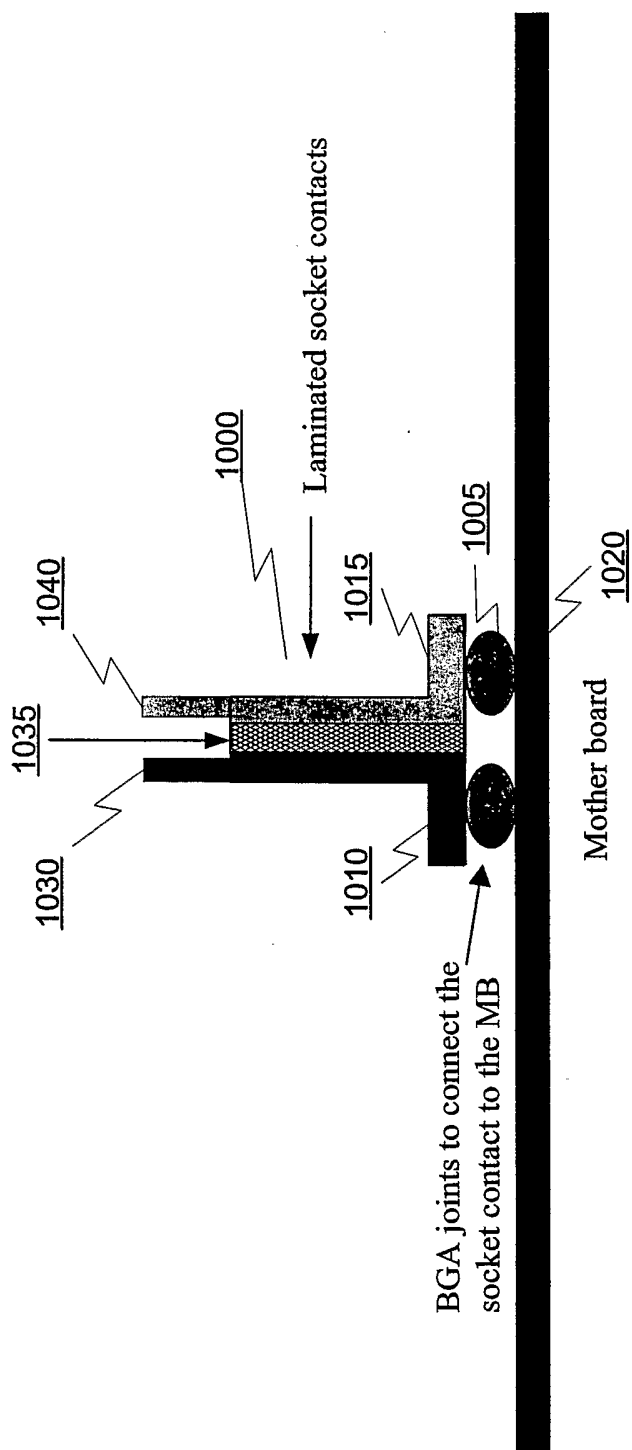


Figure 10

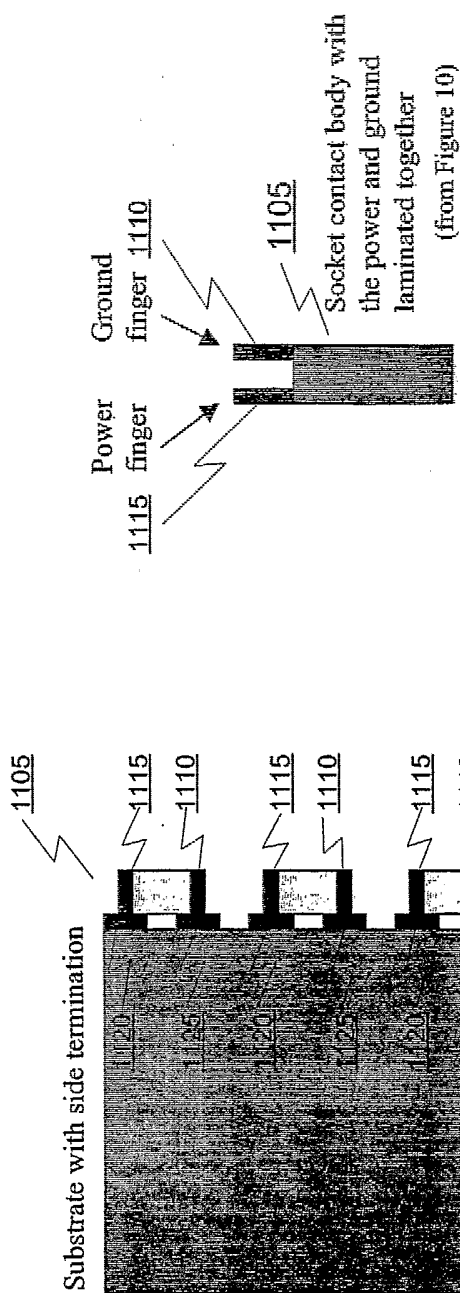


Figure 11